**Product data sheet** 

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT186A "full pack" plastic package intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. This "series CT" triac will commutate the full RMS current at the maximum rated junction temperature  $(T_{j(max)} = 150 \, ^{\circ}\text{C})$  without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

### 2. Features and benefits

- 3Q technology for improved noise immunity
- · High commutation capability with maximum false trigger immunity
- High junction operating temperature capability (T<sub>j(max)</sub> = 150 °C)
- High immunity to false turn-on by dV/dt
- High voltage capability
- · Isolated mounting base package
- Less sensitive gate for very high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

# 3. Applications

- Applications subject to high temperature (T<sub>i(max)</sub> = 150 °C)
- Electronic thermostats
- High power motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids
- · Refrigeration and air conditioning compressor

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit				
Absolute	Absolute maximum rating							
$V_{DRM}$	repetitive peak off-state voltage		800	V				
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; $T_h \le 67 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	16	А				
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $t_p$ = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	140	Α				
		full sine wave; $t_p$ = 16.7 ms; $T_{j(init)}$ = 25 °C	150	Α				
T <sub>j</sub>	junction temperature		150	°C				

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics			'		
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+ T_j = 25 ^{\circ}\text{C}; Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2 + G-$ $T_j = 25 \text{ °C}; Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2- G-$ $T_j = 25 ^{\circ}C; Fig. 7$	2	-	35	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	35	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 18 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.3	1.5	V
Dynamic	characteristics			'		
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	500	-	-	V/µs
		$V_{DM}$ = 536 V; $T_j$ = 150 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	200	-	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 150 ^{\circ}\text{C}; I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20  \text{V}/\mu\text{s};$ gate open circuit; snubberless condition	8	-	-	A/ms

# 5. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	T2—T1
2	T2	main terminal 2		G sym051
3	G	gate		Syllios
mb	n.c.	mounting base; isolated		
			$ \left(\begin{array}{ccc}                                   $	

# 6. Ordering information

**Table 3. Ordering information** 

Type number	Package				
	Name	Description	Version		
BTA316X-800CT	TO-220F	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 'full pack'	SOT186A		

# 7. Marking

Table 4. Marking codes

Type number	Marking codes
BTA316X-800CT	BTA316X-800CT

BTA316X-800CT

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# 8. Limiting values

#### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage		800	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; $T_h \le 67 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	16	А
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $t_p$ = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	140	А
		full sine wave; $t_p = 16.7 \text{ ms}$ ; $T_{j(init)} = 25 \text{ °C}$	150	А
I <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10ms; sine wave	98	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 70mA	100	A/µs
I <sub>GM</sub>	peak gate current		2	А
$P_GM$	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T <sub>stg</sub>	storage temperature		-40 to 150	°C
T <sub>j</sub>	junction temperature		150	°C

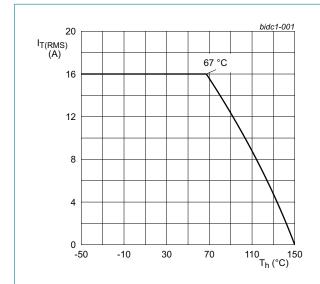


Fig. 1. RMS on-state current as a function of heatsink temperature; maximum values

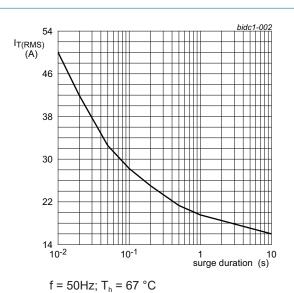


Fig. 2. RMS on-state current as a function of surge duration; maximum values

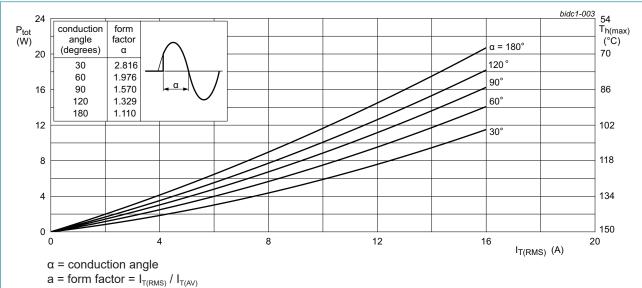


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

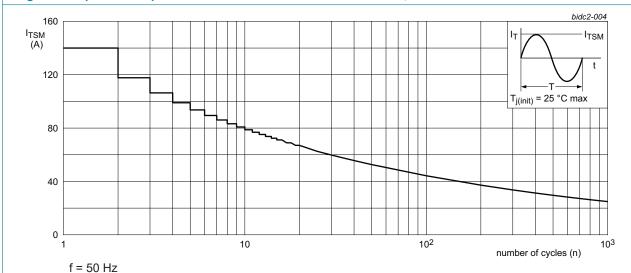
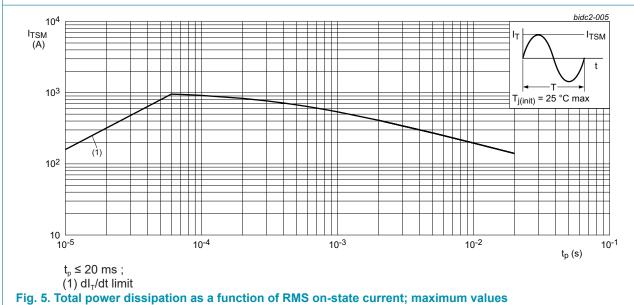


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



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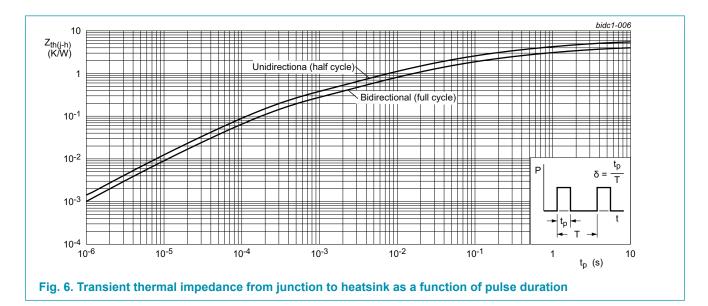
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### 9. Thermal characteristics

### **Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to	with heatsink compound; Fig. 6	-	-	4	K/W
	heatsink	without heatsinkcompound; Fig. 6	-	-	5.5	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



### 10. Isolation characteristics

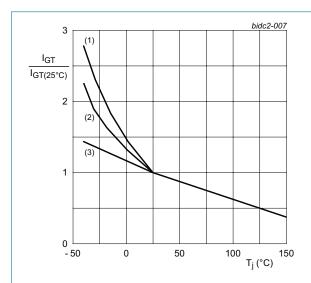
#### **Table 6. Isolation characteristics**

S	Symbol	Parameter	Conditions	Min	Тур	Max	Unit
٧	/isol(RMS)	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C	Sisol	isolation capacitance	from cathode to external heatsink	-	10	-	PF

## 11. Characteristics

### Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					'
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G+;$ $T_j = 25 \text{ °C; } Fig. 7$	2	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } \underline{Fig. 7}$	2	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2-\text{ G-;} $ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	2	-	35	mA
I <sub>L</sub>	latching current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;} $ $T_j = 25 \text{ °C; } \underline{\text{Fig. 8}}$	-	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	60	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	50	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	35	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 18 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.3	1.5	V
$V_{GT}$	gate trigger voltage	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 11	-	0.8	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C	-	-	2	mA
Dynamic o	haracteristics		'		'	
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_{j}$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	500	-	-	V/µs
		$V_{DM}$ = 536 V; $T_{j}$ = 150 °C; $(V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	200	-	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D = 400 \text{ V; } T_j = 150 ^{\circ}\text{C; } I_{T(RMS)} = 16 \text{ A; } dV_{com}/dt = 20 \text{ V/}\mu\text{s; gate open circuit; } snubberless condition}$	8	-	-	A/ms



- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

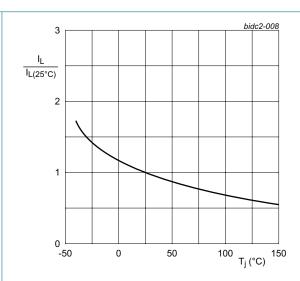


Fig. 8. Normalized latching current as a function of junction temperature

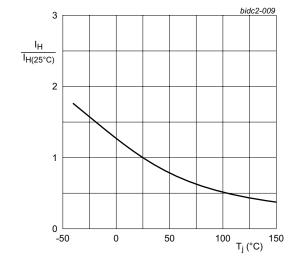
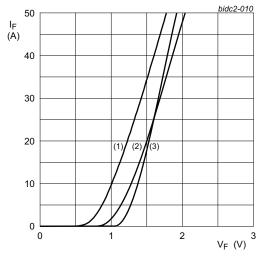


Fig. 9. Normalized holding current as a function of junction temperature



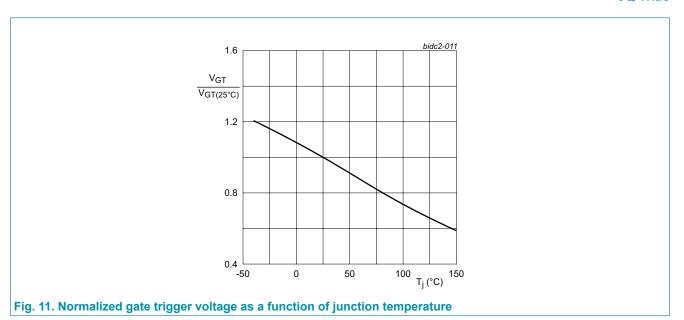
 $V_o = 1.053 \text{ V}; R_s = 0.0216 \Omega$ 

(1) T<sub>i</sub> = 150 °C; typical values

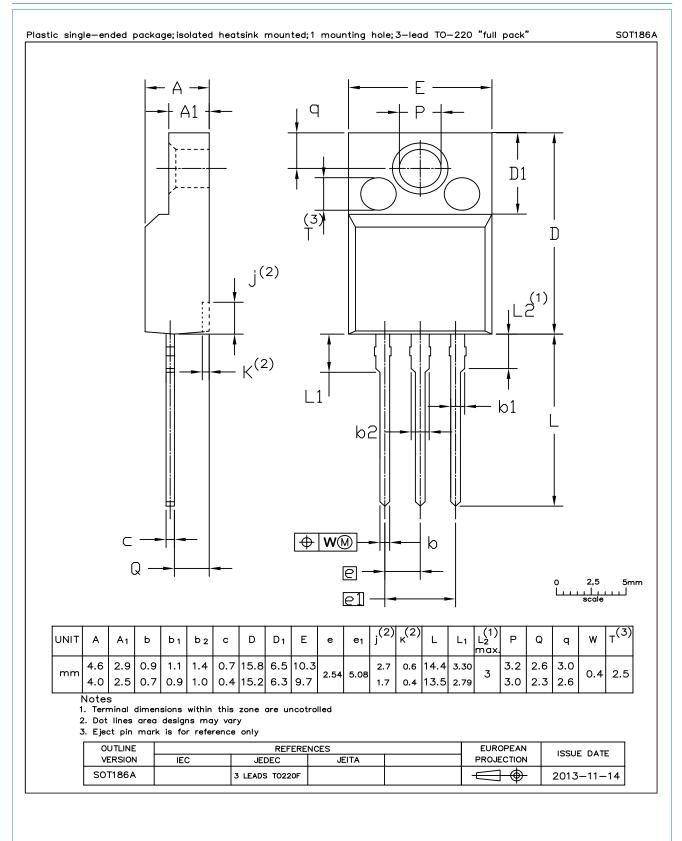
(2) T<sub>i</sub> = 150 °C; maximum values

(3) T<sub>i</sub> = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage



# 12. Package outline



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## 13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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